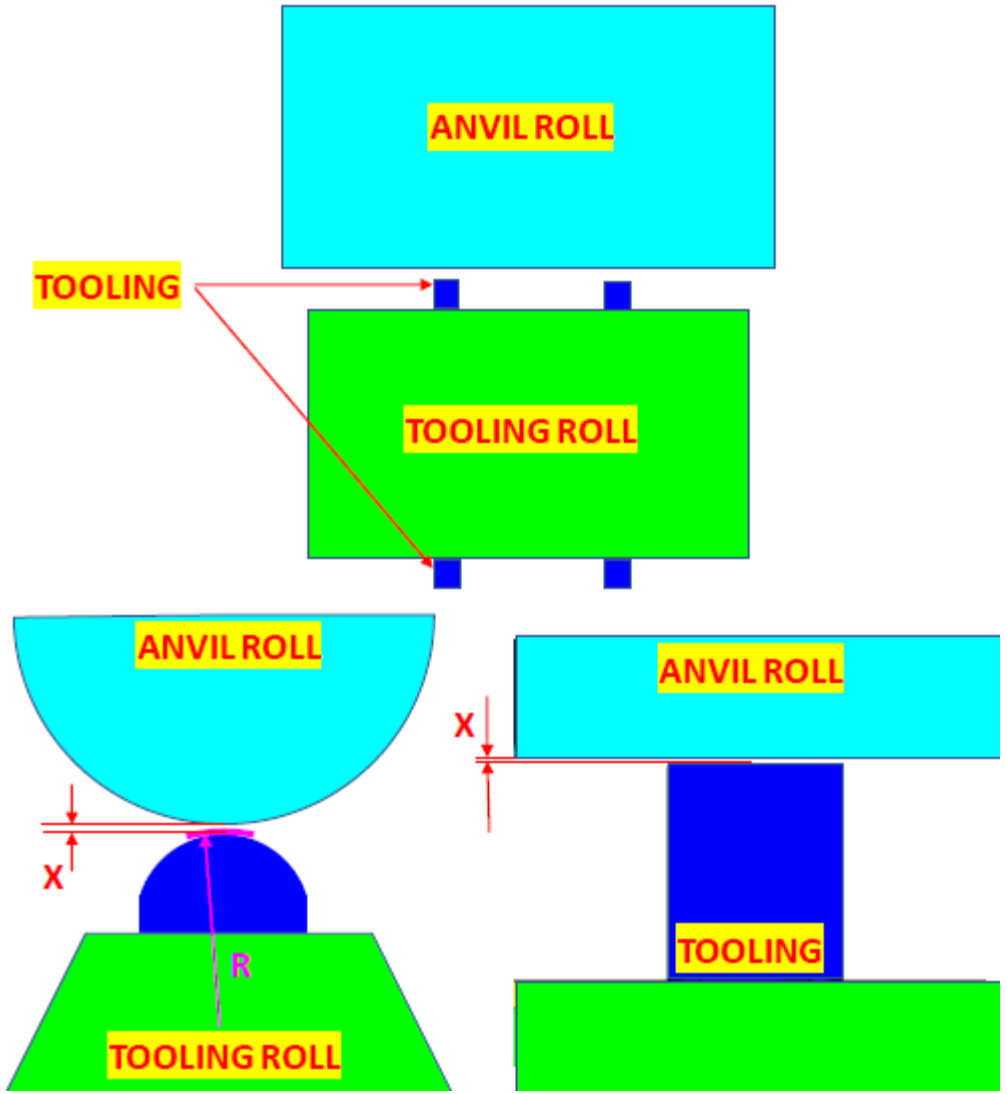
CPW Micron Gap Measurement

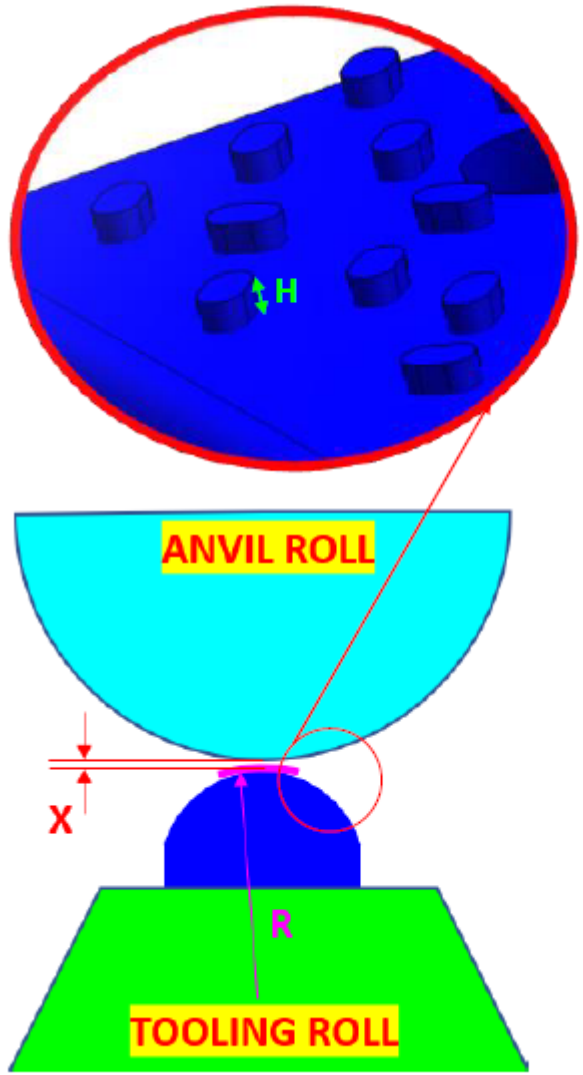
CPW Bonding Tech

- CPW Bonding Tech is a common bonding technology in paper industry
- The bond is achieved by squeezing materials through a Tooling (Tooling Roll) and Anvil (Anvil Roll) with a micron-tight gap
- Tooling has a pattern that follows the same curvature of the rotating roll (**R**)
- Micron size gap must exist between Tooling & Anvil (**X**) – no nub touches anvil



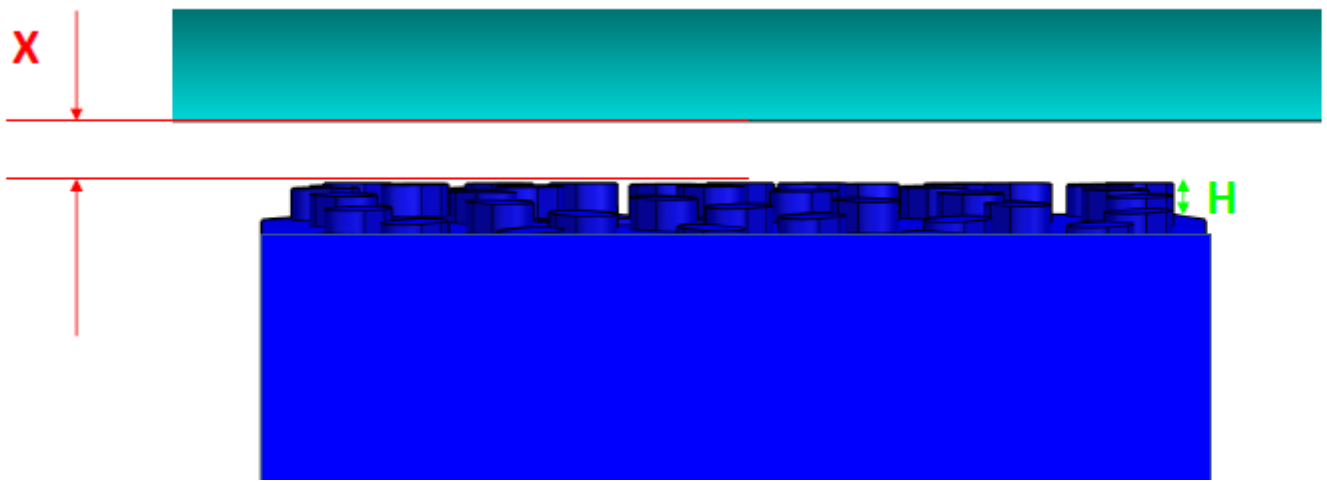
X-Micron Gap

- Measuring (**X**) is required to have the correct nub height (**H**) designed in
- Having too tall of a nub, would damage the nubs (hitting anvil)
- Having too short of a nub, would lead to poor/no bond (no product)



X-Micron Gap

- Dimension (**X**) is expected to be between **20-40 Microns**
- Fabrication Nub-to-Nub variations occur, i.e. (**H**) is not always consistent
- Nubs come in waves which are not on the same row-position



Do you have any suggestions how to measure this X Gap ?